

# 3.2x1.0 x1.5mm Side View Chip LED

### **OSXX1204C1E**

### **■Features**

- · Single chip
- · Super high brightness of surface mount LED
- Compact package outline
   (L x W x T) of 3.2mm x 1.0mm x1.5mm
- · Compatible to IR reflow soldering.

# **■**Applications

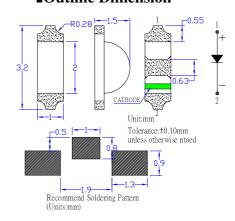
- Backlighting (switches, keys, etc.)
- Marker lights (e.g. steps, exit ways, etc.)

# ■Absolute Maximum Rating

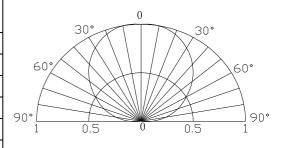
# (Ta=25°C)

#### Value Item Symbol Unit WA/M5/K4/B5/G5 G8/Y5/O5/R5 DC Forward Current $I_F$ 20 20 mΑ Pulse Forward Current# 80 100 $I_{FP}$ mA Reverse Voltage $V_R$ 5 5 V Power Dissipation 68 $P_{D}$ mW $^{\circ}$ C -40 ~ +85 Operating Temperature Topr $^{\circ}$ C Storage Temperature Tstg -40~ +85 Lead Soldering Temperature Tsol 260°C/10sec

# **Outline Dimension**



# Directivity



#Pulse width Max 0.1ms, Duty ratio max 1/10

# **■**Electrical -Optical Characteristics

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				$V_{F}(V)$		$I_R(\mu A)$	I	v(mcd)			$\lambda D(nm)$		2θ1/2	2θ1/2(deg)	
Part Number	Color		Min.	Тур.	Max.	Max.	Min.	Тур.	Max.	Min.	Тур.	Ma	x. 7	Гур.	
				I <sub>F</sub> =10mA			V <sub>R</sub> =5V	I <sub>F</sub> =10mA							
OSWA1204C1E	White	WA		-	2.8	3.4	10	150	250	-	8200K	10500	K	12500K	120
OSM51204C1E	Warm White	M5		-	2.8	3.4	10	150	250	1	2700K	2900	K	3300K	120
OSK41204C1E	Pink	K4		-	2.8	3.4	10	50	100	1	1	X:0.22 Y	:0.08	-	120
OSB51204C1E	Blue	B5		-	2.8	3.4	10	70	110	1	462	467		472	120
OSG51204C1E	True Green	G5		-	2.8	3.4	10	200	350	1	518	522		526	120
OSG81204C1E	Yellow Green	G8		-	1.8	2.4	10	15	30	1	566	569		572	120
OSY51204C1E	Yellow	Y5		-	1.8	2.4	10	40	80	1	586	589		592	120
OSO51204C1E	Orange	O5		-	1.8	2.4	10	40	80	-	600	605		610	120
OSR51204C1E	Red	R5		-	1.8	2.4	10	40	80	-	617	621		625	120

<sup>\*1</sup> Tolerance of measurements of chromaticity coordinate is ±10%

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<sup>\*2</sup> Tolerance of measurements of dominant wavelength is ±1nm

<sup>\*3</sup> Tolerance of measurements of luminous intensity is ±15%

<sup>\*4</sup> Tolerance of measurements of forward voltage is ±0.1V



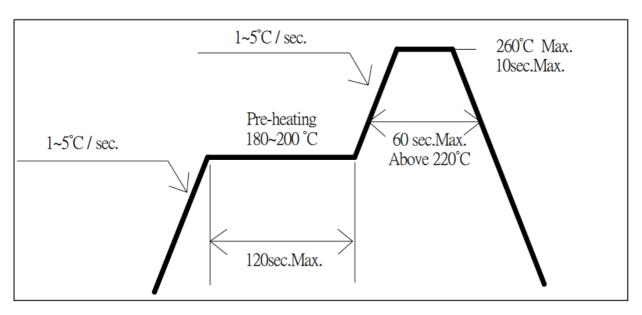
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### **■** Soldering Conditions

	Reflow Soldering	Hand Soldering			
Pre-Heat	180 ~ 200°C				
Pre-Heat Time	120 sec. Max.				
Peak temperature	260°C Max.	Temperature	350°C Max.		
Dipping Time	10 sec. Max.	Soldering time	3 sec. Max.		
Condition	Refer to Temperature-profile		(one time only)		

# • Reflow Soldering Condition(Lead-free Solder)



- \*Recommended soldering conditions vary according to the type of LED
- \*Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.
- \*A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- •All SMD LED products are pb-free soldering available.
- Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.





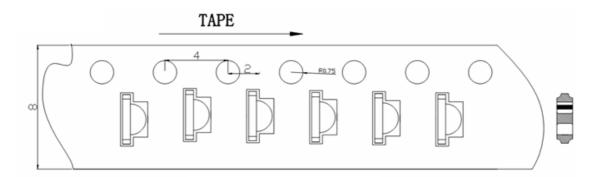




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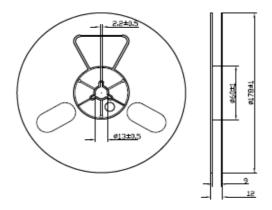
### **TAPING**



### ■ Reel Dimensions

#### Notes:

- 1. Unit: mm
- 2. 3000pcs/Reel



## **■** Cautions:

- 1. After open the package, the LED's floor life is 4 Weeks under 30°C or less and 60%RH or less(MSL:2a).
- 2. Heat generation must be taken into design consideration when using the LED.
- 3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
- 4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
- 5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
- 6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
- 7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.

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